JOCDA3ABN-W8

(Temperature=25°C)

Parameter		Symbol	Value	Unit
LED	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	100	mW
Detector	Output Voltage	V_O	35	V
	Supply Voltage	V_{CC}	35	V
	Power Dissipation	P_C	400	mW
Isolation Voltage		V_{iso}	7500	Vrms
Operating Temperature		T_{opr}	-40~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Total Power Dissipation		P_{tot}	500	mW
Soldering Temperature		T_{sol}	260	

: 100μs pulse, 100Hz frequency

: AC for 1minute, R.H.=40~60%

	Low Level Output Voltage	V_{OL}	I_O=100mA	-	0.2	0.5	V
	Threshold Input Current	I_{FLH}	V_O 5V	-	1.2	5	mA
	Threshold Input Voltage	V_{FHL}	V_O 5V	0.8	-	-	V
	Supply Voltage	V_{CC}	-	15	-	30	V
	UVLO Threshold	VUVLO+	V_O 5V, I_F=10mA	12.1	12.8	13.5	V
		VUVLO-	V_O 5V, I_F=10mA	11.1	11.8	12.4	V

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Propagation Delay Time to High Output Level	t_{PLH}	R_g=10Ω, C_g=25nF, f=20kHz, Duty Cycle=50%, I_F=7mA, V_{CC}=30V	30	-	500	ns
Propagation Delay Time to Low Output Level	t_{PHL}		30	-	500	
Propagation Delay Difference Between Any Two Parts	t_{PHL}- t_{PLH}		-	-	350	
Output Rise Time (10 to 90%)	t_r	R_g=10Ω, C_g=25nF, I_F=0→7mA, V_{CC}=30V	-	50	-	
Output Fall Time (90 to 10%)	t_f	R_g=10Ω, C_g=25nF, I_F=7→0mA, V_{CC}=30V	-	50	-	
Common Mode Transient Immunity at High Level Output	$\|CM_H\|$	I_F=7mA V_{CC}=30V, T_a=25 , V_O(min)=26V V_{CM}=1500Vpp	±35	-	-	kV/μs
Common Mode Transient Immunity at Low Level Output	$\|CM_L\|$	I_F=0mA V_{CC}=30V, T_a=25 , V_O(max)=1V V_{CM}=1500Vpp	±35	-	-	kV/μs

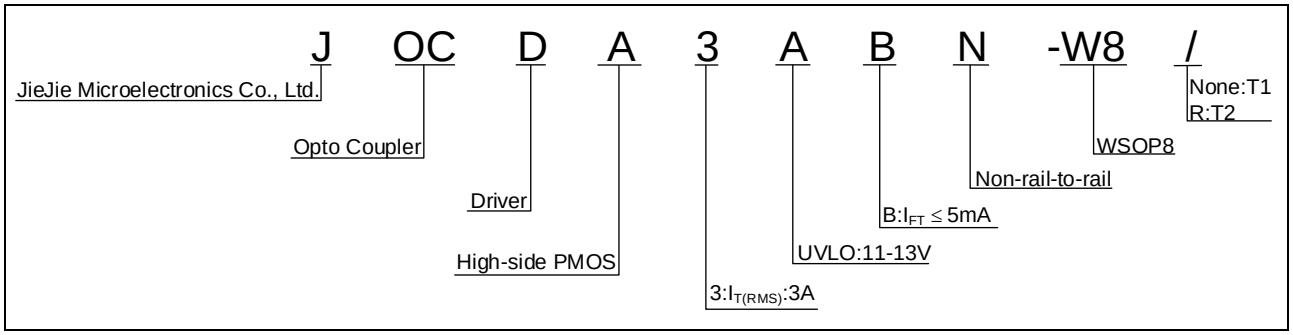
All Typical values at T_a=25

: Input signal (f=25kHz,duty=50%, tr=tf=5ns or less). C_L is less than 15 pF which includes probe and stray wiring capacitance.

: CM_H is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic high state (VO 26V).

: CML is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic low state (VO 1V).

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WSOP8	1200 Units/Reel	1 Reel/Inner box	5 Inner box/Outer box =6k Units

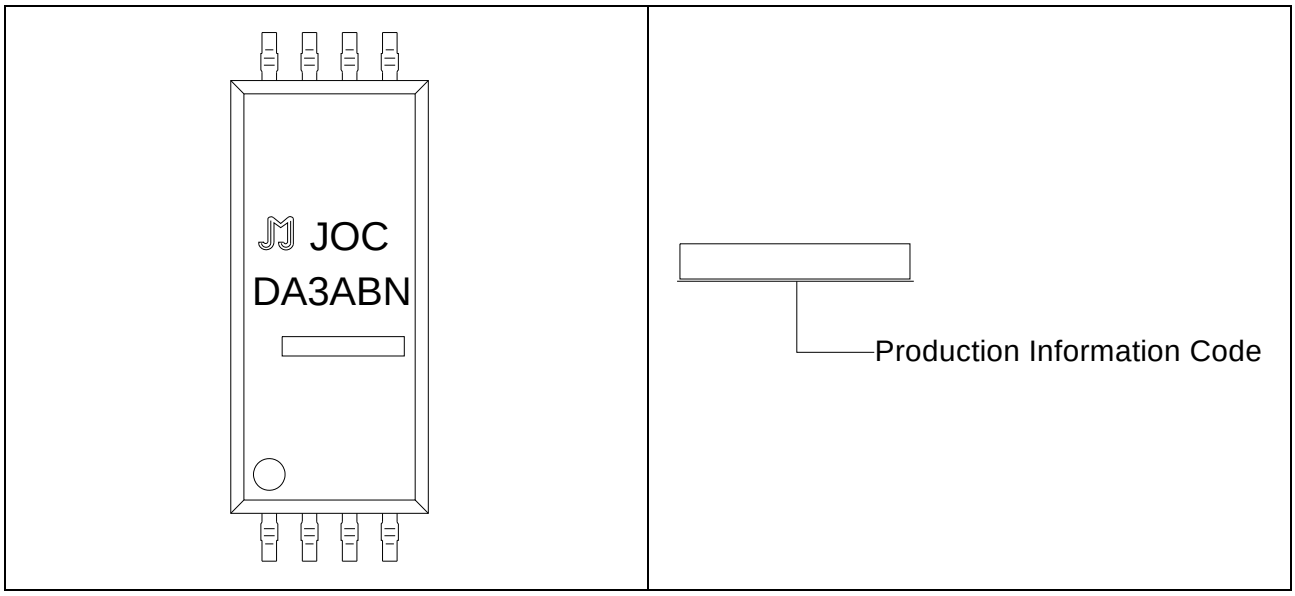


FIG.1: Forward Current vs. Forward Voltage

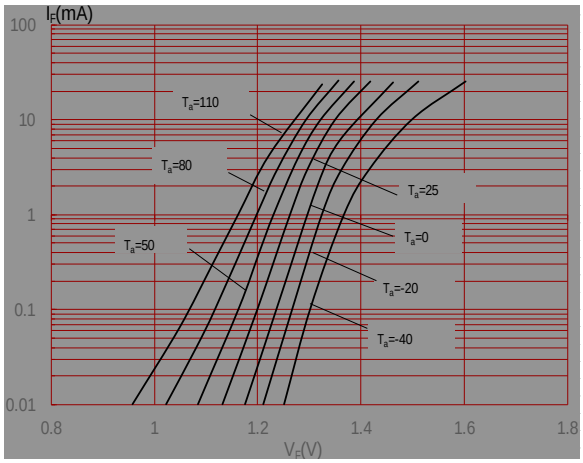


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

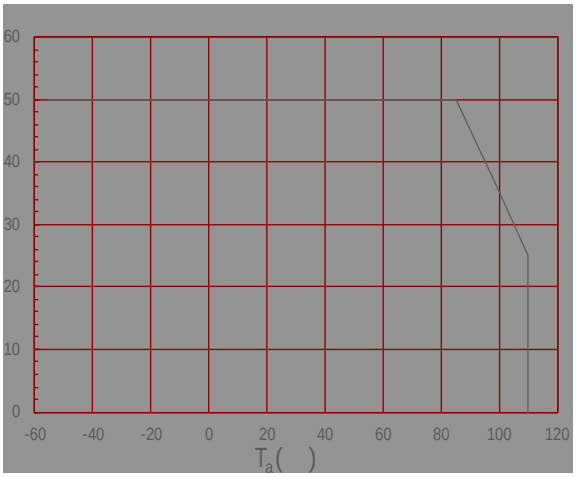
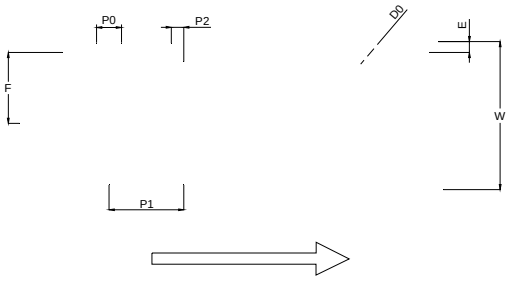


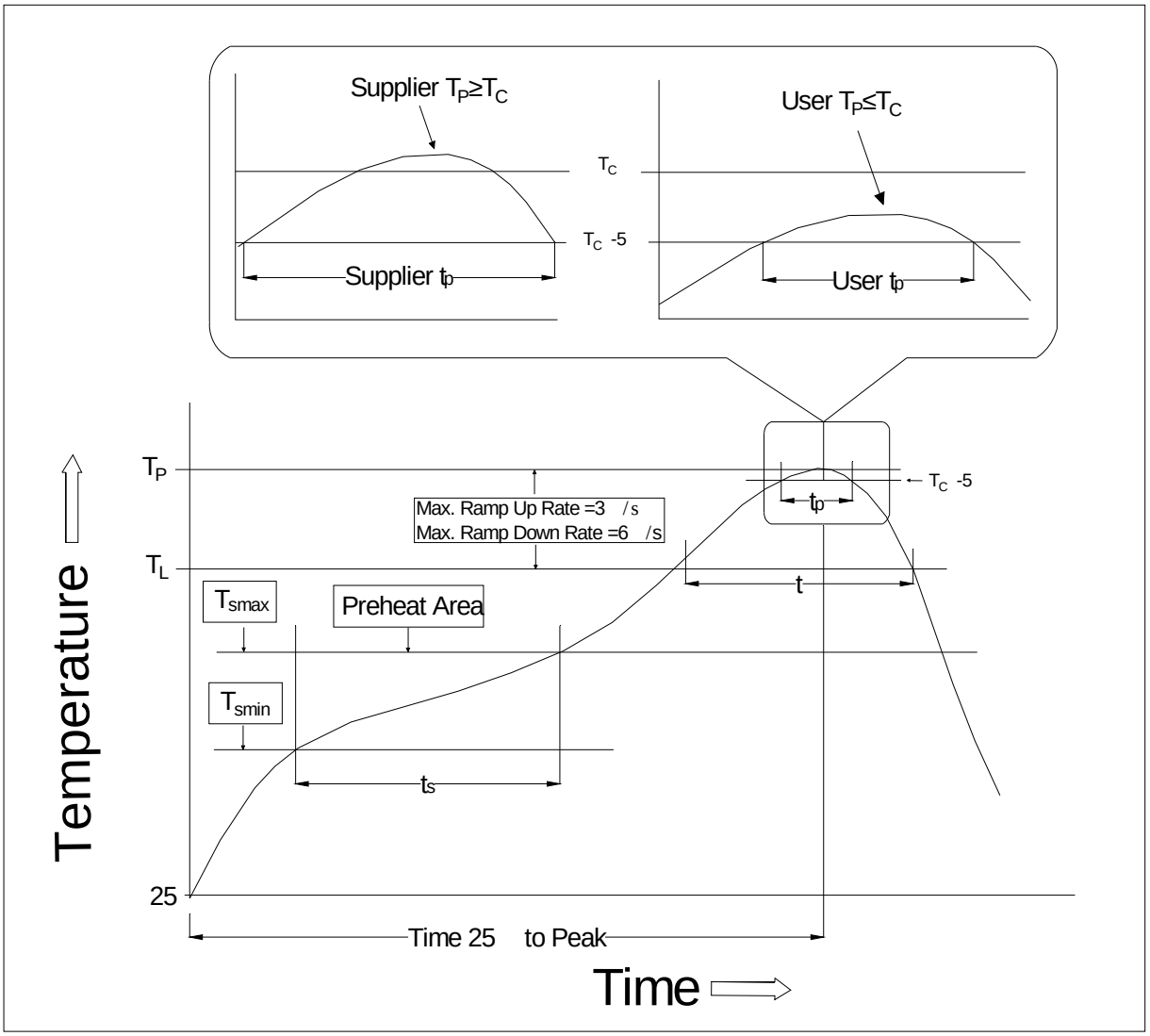
FIG.7: Low-level Output Voltage vs. Ambient Temperature

FIG.8: High-level Output Voltage vs. Ambient Temperature

FIG.13: Propagation Delay Time vs. Supply Voltage

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P0
P2
D0
E
F
W
P1



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

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